WHAT IS CLAIMED IS:

1. A package structure, comprising:

a first insulation layer;

a first redistribution structure located in the first insulation layer and exposed from a bottom surface of the first insulation layer, wherein the first redistribution structure comprises at least one first redistribution layer;

a second redistribution structure, wherein a part of the second redistribution structure is disposed on a part of a top surface of the first insulation layer, and the other part of the second redistribution structure is located in the first insulation layer, wherein the second redistribution structure comprises at least one second redistribution layer;

at least one electronic component embedded within the first insulation layer, disposed on the first redistribution structure, and comprising plural conducting terminals, wherein at least one of the conducting terminals is connected with the second redistribution structure;

a second insulation layer disposed on the other part of the top surface of the first insulating layer and the second redistribution structure;

a first heat spreader disposed on the second insulation layer;

a heat dissipation substrate disposed on the bottom surface of the first insulation layer;

a second heat spreader disposed on the heat dissipation substrate; and

plural thermal conduction structures embedded within the first insulation layer, wherein at least one of the plural thermal conduction structures is connected with at least one of the first redistribution structure and the second redistribution structure, and the plural thermal conduction structures are respectively exposed from the opposite sides of the first insulation layer to form plural pins.

2. The package structure according to claim 1, wherein the least one electronic component comprises a Wide Band Gap power semiconductor device.

3. The package structure according to claim 1, wherein the package structure further comprises at least one heat dissipation device disposed on at least one of the first heat spreader and the second heat spreader.

4. The package structure according to claim 1, wherein the package structure further comprises a molding element surrounding the first insulation layer, the first redistribution structure, the second redistribution structure, the second insulation layer, the first heat spreader, the heat dissipation substrate, and the second heat spreader to package a part of the first insulation layer, a part of the first redistribution structure, a part of the second redistribution structure, a part of the second insulation layer, a part of the first heat spreader, a part of the heat dissipation substrate, and a part of the second heat spreader, wherein the plural pins of the plural thermal conduction structures are respectively extended outwardly along a horizontal direction from the molding element.

5. The package structure according to claim 1, wherein one of the plural thermal conduction structures is thinner than the other of the plural thermal conduction structures, the thinner one of the plural thermal conduction structures is adapted to be a signal path, and the thicker one of the plural thermal conduction structures is adapted to be at least one of a high current path and a high voltage path.

6. The package structure according to claim 1, wherein the at least one electronic component comprises a first electronic component, and the plural conducting terminals of the first electronic component are formed on a first surface of the first electronic component.

7. The package structure according to claim 6, wherein the at least one first redistribution layer is located in the first insulation layer and exposed from the bottom surface of the first insulation layer, the first electronic component is attached on the corresponding first redistribution layer through a fixing material, and each of the plural thermal conduction structures is disposed on the corresponding first redistribution layer.

8. The package structure according to claim 6, wherein the second redistribution structure comprises:

the at least one second redistribution layer disposed on a part of the top surface of the first insulation layer;

at least one first conductive via formed in the first insulation layer, wherein the at least one first conductive via is in contact with the corresponding second redistribution layer and connected with the corresponding conducting terminal of the first electronic component; and

at least one second conductive via formed in the first insulation layer, wherein the at least one second conductive via is in contact with the corresponding second redistribution layer and connected with the corresponding thermal conduction structure.

9. The package structure according to claim 1, wherein the at least one electronic component comprises at least one second electronic component and at least one first electronic component, wherein the plural conducting terminals of the first electronic component are formed on a first surface of the first electronic component, at least one of the plural conducting terminals of the second electronic component is formed on a second surface of the second electronic component, and the others of the plural conducting terminals of the second electronic component are formed on a first surface of the second electronic component.

10. The package structure according to claim 9, wherein the first redistribution structure comprises:

the at least one first redistribution layer located in the first insulation layer and exposed from the bottom surface of the first insulation layer; and

at least one second redistribution layer, wherein the at least one second redistribution layer of the first redistribution structure is located in the first insulation layer and exposed from the bottom surface of the first insulation layer.

11. The package structure according to claim 10, wherein at least one of the plural thermal conduction structures and the at least one first electronic component are respectively disposed on the corresponding first redistribution layer, and the at least one second electronic component is disposed on the corresponding second redistribution layer.

12. The package structure according to claim 11, wherein the second redistribution structure comprises:

at least one third redistribution layer disposed on a part of the top surface of the first insulation layer;

at least one fourth redistribution layer disposed on a part of the top surface of the first insulation layer;

at least one first conductive via formed in the first insulation layer, wherein the at least one first conductive via is in contact with the corresponding third redistribution layer and connected with at least one of the corresponding conducting terminal formed on the first surface of the second electronic component and the corresponding conducting terminal formed on the first electronic component;

at least one second conductive via formed in the first insulation layer, wherein the at least one second conductive via is in contact with the corresponding third redistribution layer and connected with the corresponding thermal conduction structure;

at least one third conductive via formed in the first insulation layer, wherein the at least one third conductive via is in contact with the corresponding fourth redistribution layer and connected with the corresponding conducting terminal of the first electronic component; and

at least one fourth conductive via formed in the first insulation layer, wherein the at least one fourth conductive via is in contact with the corresponding fourth redistribution layer and connected with the second redistribution layer of the first

redistribution structure.

13. A power module, comprising:

at least one printed circuit board; and

at least one package structure, comprising:

a first insulation layer;

a first redistribution structure located in the first insulation layer and exposed from a bottom surface of the first insulation layer;

a second redistribution structure, wherein a part of the second redistribution structure is disposed on a part of a top surface of the first insulation layer, and the other part of the second redistribution structure is located in the first insulation layer;

at least one electronic component embedded within the first insulation layer, disposed on the first redistribution structure, and comprising plural conducting terminals, wherein at least one of the plural conducting terminals is connected with the second redistribution structure;

a second insulation layer disposed on the other part of the top surface of the first insulating layer and the second redistribution structure;

a first heat spreader disposed on the second insulation layer;

a heat dissipation substrate disposed on the bottom surface of the first insulation layer;

a second heat spreader disposed on the heat dissipation substrate; and

plural thermal conduction structures embedded within the first insulation layer, wherein at least one of the plural thermal conduction structures is connected with at least one of the first redistribution structure and the second redistribution structure, and the plural thermal conduction structures are respectively extended outwardly along a horizontal direction from the opposite sides of the first insulation layer to form plural pins to be inserted into the at least one printed circuit board.

14. The power module according to claim 13, wherein the plural pins are extended outwardly along a horizontal direction from the package structure and bent toward the at least one printed circuit board to be inserted into the at least one printed circuit board.

15. The power module according to claim 14, wherein the at least one of the pins comprises at least one of a press-fit-type pin and a fastener pin.

16. The power module according to claim 14, wherein the at least one the package structure comprises plural package structures, and at least one printed circuit board comprises two printed circuit boards, wherein the plural package structures are arranged in parallel with each other and located between the two printed circuit boards, wherein the plural pins of one of the package structures are inserted into the two printed circuit boards, respectively.

17. The power module according to claim 13, wherein the least one electronic component comprises a Wide Band Gap power semiconductor device.

18. The power module according to claim 13, wherein the at least one package further comprises a molding element surrounding the first insulation layer, the first redistribution structure, the second redistribution structure, the second insulation layer, the first heat spreader, the heat dissipation substrate, and the second heat spreader to package a part of the first insulation layer, a part of the first redistribution structure, a part of the second redistribution structure, a part of the second insulation layer, a part of the first heat spreader, a part of the heat dissipation substrate, and a part of the second heat spreader, wherein the plural pins of the plural thermal conduction structures are respectively extended outwardly along a horizontal direction from the molding element.

19. The power module according to claim 13, wherein one of the plural thermal conduction structures is thinner than the other of the plural thermal conduction structures, the thinner one of the plural thermal conduction structures is configured to be a signal path, and the thicker one of the plural thermal

conduction structures is configured to be at least one of a high current path and a high voltage path.

20. The power module according to claim 13, wherein the at least one electronic component comprises at least one second electronic component and at least one first electronic component, wherein the plural conducting terminals of the first electronic component are formed on a first surface of the first electronic component, at least one of the plural conducting terminals of the second electronic component is formed on a second surface of the second electronic component, and the others of the plural conducting terminals of the second electronic component are formed on a first surface of the second electronic component.